Busine	ess Unit & Req. #1905 & TBD	ECCN	N: Total Amoun	t: \$1,000,000		
Note:			ument, open to public inspection; therefore, andable.	you should be certain		
	SOLE SOURCE CERTIFICATION	the following	uirement of University of Florida Rule No. 6C1 is submitted in support of this request for authout bidding, the items available from only	uthority to		
Note:	be provided. Best Price alone cannot of supply, best price must be determ	t be used for sole s ined through the c				
A. Sole	Source Vendor Company Name: Va	anguard Autom	ation Inc. (a Mycronic Company)			
	ntact Person: Sebastian Skacel					
	Address: Gablonzer Strasse 10 76185 Karlsruhe, Germany					
Tel	lephone: +49 721 5966 063 € Fa	ax:	_{Email:} sebastian.skacel@r	nycronic.com		
B. Describe in lay language, what the item/service is and how it is to be used in your area of research. (cont. P2)						
	Vanguard Automation offers machines and processes for 3D nano-printing in the field of photonic					
	integration and packaging. Unique to this machine is the offering of photonic wire bonding and					
	C. What feature or special condition of this commodity/service is unique and cannot be obtained from any other source? Why are these features or special conditions important to the research? (cont. P2)					
pho			otical chip-to-chip and chip-to-optical t chip facet interfaces are not availab			
If N	Is this product being purchased directly from the manufacturer? If No, is it available from more than one dealer? If Yes, it is available from more than one dealer, why can this item not be bid? (cont. P2)					
3D	This equipment is only available from this OEM providing the service of photonic wire bonding. A regular 3D printer has not the capability of writing optical low-loss micro structures suitable for optical coupling between fiber-to-chip and chip-to-chip. Vanguard Automation offers a unique value proposition.					
E. Prior	Prior to submitting this requisition, did you investigate other possible sources? If Yes: 1) Did you obtain quotes from the other sources? Yes No If Yes, attach copies. 2) Is this Vendor's price lower than the other sources? Yes No If No, justify the additional cost below.					
The			such capability (e.g. photonic wire bo			
F. What	t efforts have been made to obtain the	best price possibl	e? Why do you feel this price is fair and rea	sonable? (cont. P2)		
Sev	Several rounds of negotiations had occured. We obtained two rounds of discount from the vendor. Several items are quote are offered free of charge, and others received steep discounts.					
	the undersigned, certify the above to be ersigned does not have a financial inter		to the best of my / our knowledge and belief named vendor.	and the user and /		
	DEPARTMENT APPROVAL	_	PURCHASING APPROVAL			
I hereby certify the validity of the information and feel confident the Sole Source Certification will meet University criteria and would withstand any audit or vendor protest.		This acquisition is approved as a non-competitive purchase.				
	V Joyan	4/23/2025		4-24-25		
	al Investigator's Signature	Date	Purchasing Coordinator Signature	Date		
FAILURE TO FILE A PROTEST IN ACCORDANCE WITH BOARD OF GOVERNORS (BOG) REGULATION 18.002 OR FAILURE TO POST THE BOND OR OTHER SECURITY AS REQUIRED IN THE BOG REGULATION 18.002 AND 18.003(3) SHALL CONSTITUTE A WAIVER OF PROTEST PROCEEDING.		N.J. Hevedia Purchasing Authorized Signature	4 - 28 - 2025 Date			

Sole Source Certification (Continued)

Please use the following sections to continue documentation if needed.

B. continued

... arbitrary photonic input/output (e.g. fiber to chip) connection modalities. The R&D with this equipment targets to minimize the optical losses of these to-be-established optical interfaces. In addition, advanced packaging concepts to connect arbitrary photonic chips (such as from IV and IIIV, and fibers) enables a novel design and packaging capability of photonic applications such as optical innterconects, optical transceivers and photonic AI accelerators. In order to form a usable unit, both tools are required for creating a synphony forming a stable, controllable, and high-fidelity process enabling top-of-line photonics research, especially for optical input-output.

C. continued

The capability of designing and manufacturing optical and photonic arbitrary and low-loss input-output connectors between photonic chips and/or optical fibers, enables and opens up a variety of test parameters and projects of photonic accelerators and optical interconencts including optical transceivers. This accelerates research producvity such as research publications and IP inventions. Another intent is to build digital twins for emerging optical input-output solutions with the following features: i) pluggable connector solutions, ii) spectrally broadband connectors, iii) arbitrary shaped solutions for single- and multi optical modes, chips and fibers, and iv) that feature very low optical losses.

D. continued	
E. continued	, , † ; s · .
F. continued	

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